

PATENTS  
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**IN THE CLAIMS:**

Claims 1-17 (canceled)

1           Claim 18 (currently amended). A substrate for receiving a die-down die and pro-  
2       viding electrical contacts re-orientated into a die-up orientation, the die-down die defin-  
3       ing electrical contacts, the substrate comprising:

4               a plurality of electrically conductive traces defining first contacts, the first  
5       contacts arranged to accept connector wires making electrical connections from the elec-  
6       trical contacts of a single die-down die, and

7               wherein the electrical traces define second contacts, the second contacts arranged  
8       to correspond to the die-up orientation of a single die-up die,

9               wherein the substrate can be placed into a package designed to accept a single die-  
10      up die, and wherein electrical connections may be made to the substrate's second contacts  
11      as if it were a single die-up die.

1           Claim 19 (currently amended). The substrate of claim 18 further comprising:

2               a single die-down die mounted to the substrate,

3               connector wires joining the electrical contacts of the die-down die to the  
4       first contacts on the conductive traces,

5               and

6               electrically conductive wires joining the second contacts on the conductive  
7       traces to contacts on a lead frame.

1           Claim 20. (canceled).

1           Claim 21. (currently amended). The substrate of claim 19 further comprising  
2       non-conductive means for attaching the substrate to the single die-down die.

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1 Claim 22. (previously presented). The substrate of claim 18 wherein the substrate  
2 comprises a material selected from the groups consisting of ceramic and organic.

1 Claim 23. (currently amended). The substrate of claim 19 wherein the single die-  
2 down die is an integrated circuit.

1 Claim 24. (canceled).

1 Claims 25-31 (withdrawn).

1 Claim 32 (deleted).

1 Claim 33. (deleted).

1 Claim 34. (currently amended). The die attach package of claim 45 further com-  
2 prising non-conductive means for attaching the substrate to a the single die-down die.

1 Claim 35. (previously presented). The die attach package of claim 45 wherein the  
2 substrate comprises a material selected from the groups consisting of ceramic and or-  
3 ganic.

1 Claim 36. (currently amended). The die attach package of claim 45 wherein the  
2 single die-down die is an integrated circuit.

1 Claim 37. (currently amended). The die attach package of claim 45 wherein the  
2 single die-down die includes components attached to the die-down die.

Claim 38-44. (Withdrawn).

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1       Claim 45 (currently amended). A die attach package for receiving a single die  
2   with contacts arranged in a die-up orientation, the die attach package comprising:  
3       a substrate as defined in claim 18,  
4       a lead frame with contacts,  
5       connector wires joining the second contacts on the traces to the lead frame  
6   contacts, ~~wherein the lead frame also provides means to make electrical connection to a~~  
7   ~~printed circuit board.~~